Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP MSR1003-8 AC Router(JG732A)
HP MSR1002-4 AC ROUTER(JG875A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew all screws 1, and then remove the mounting angle 2.
2. Unscrew the screws 5 on blank panel 4, then remove blank panel 4 and shielding fingers 3.
3. Unscrew all the screws 6 on top cover 7, and then remove the top cover 7.
4. Remove all the lightguides 8.
5. Unscrew all the screws 10 on power 9 and PCB 11, then remove power 9 and PCB 11.
6. Remove part 12.
7. Unscrew screw 13 and screw 16, and then remove them.
8. Unscrew screws 15 on fan 14, then remove fan 14.
9. Unscrew long screw 17 and remove part 18.
10. Remove plastic feet 19, insulating plate 20 and part 21 from the bottom.
11. Remove the plastic front panel 22 with film from the bottom.
12. Remove part 23, film 24 and film 25 from the plastic front panel 22.
13. Remove shielding fingers 26 from the bottom.
14. Remove insulating plate 27 from the top cover.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

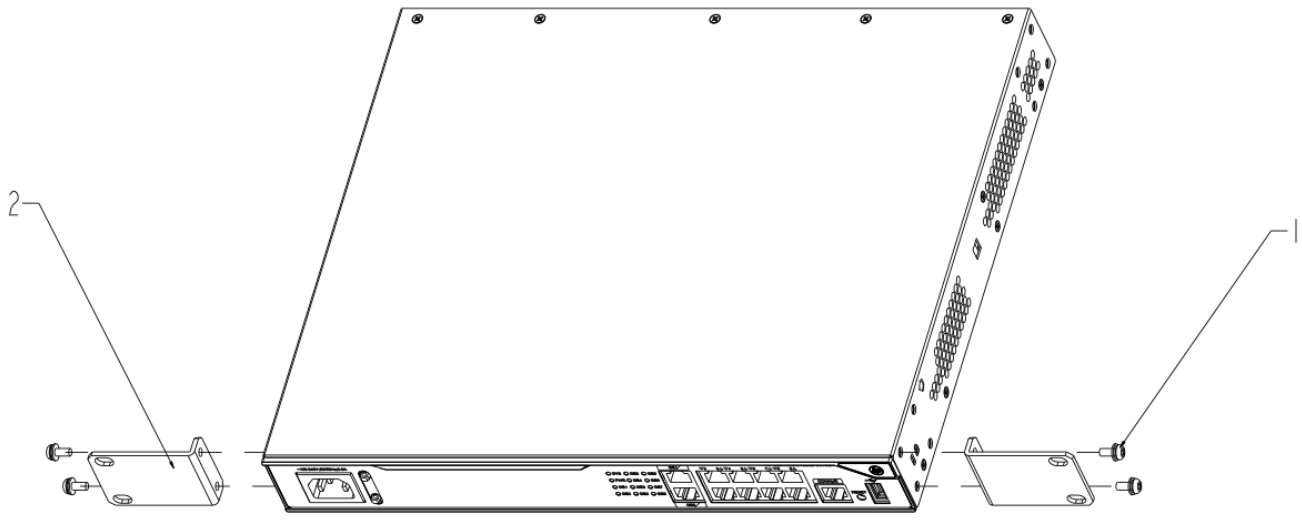

Figure 1 Remove mounting angle

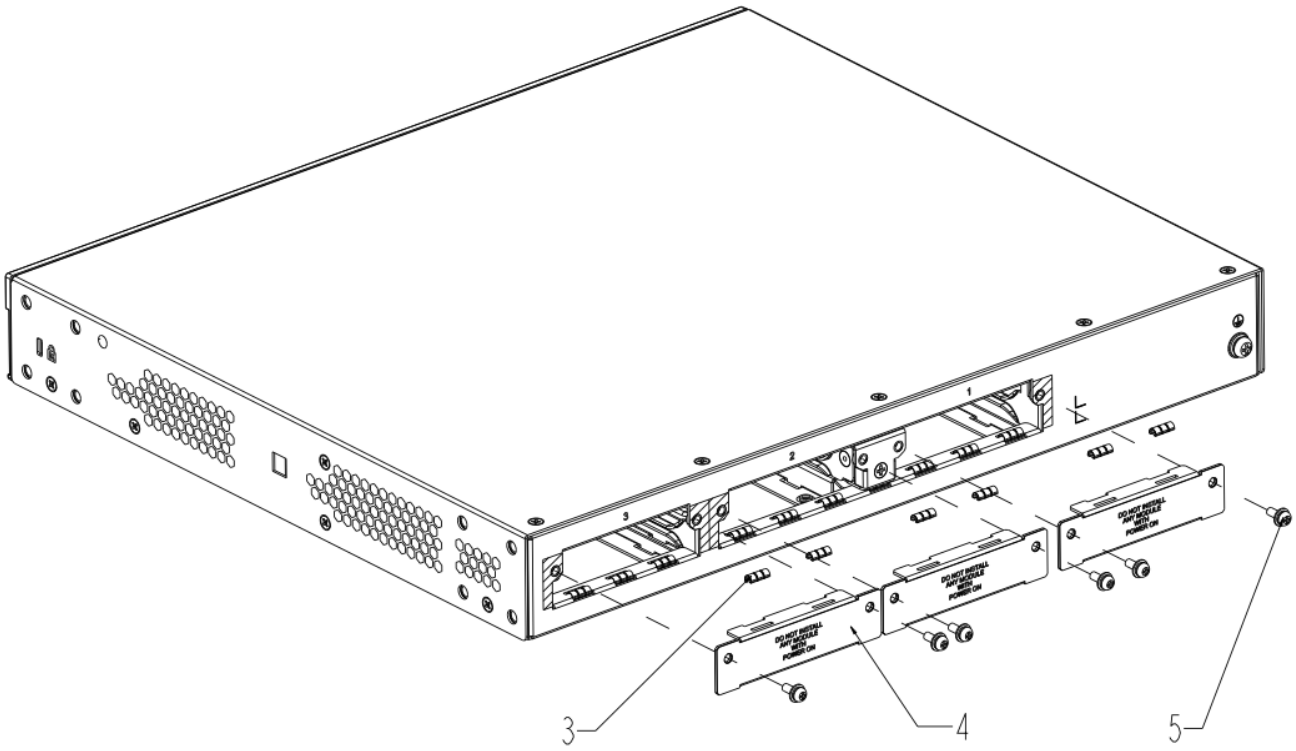

Figure 2 Treatments to the blank panel

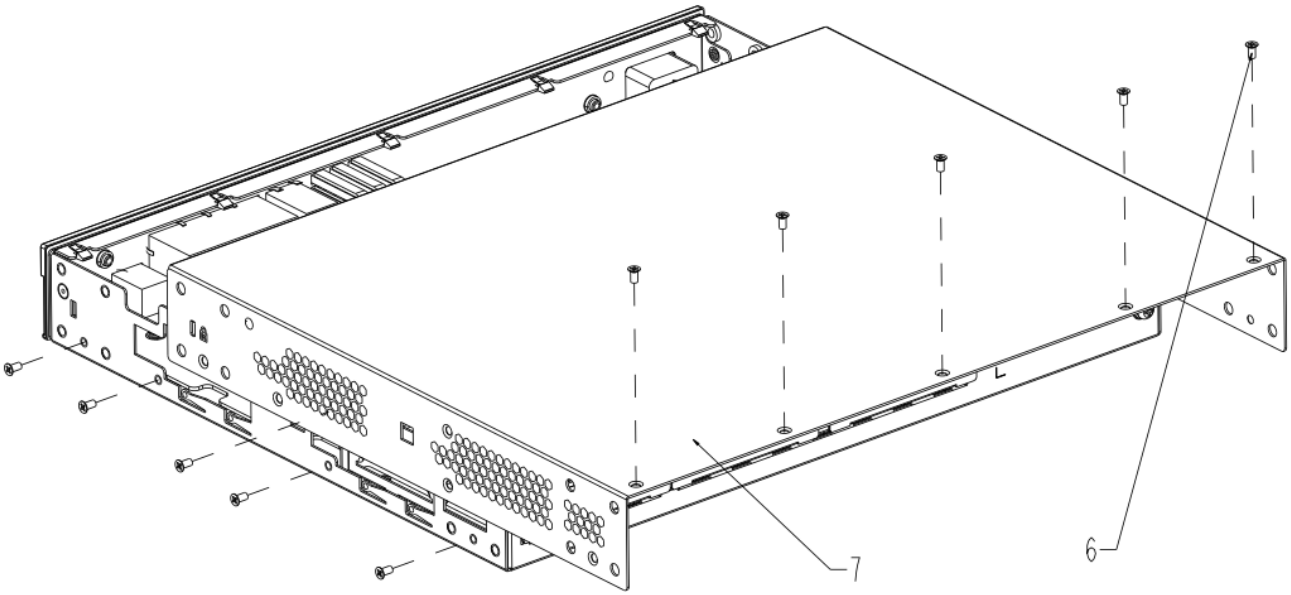

Figure 3 Treatments to the product

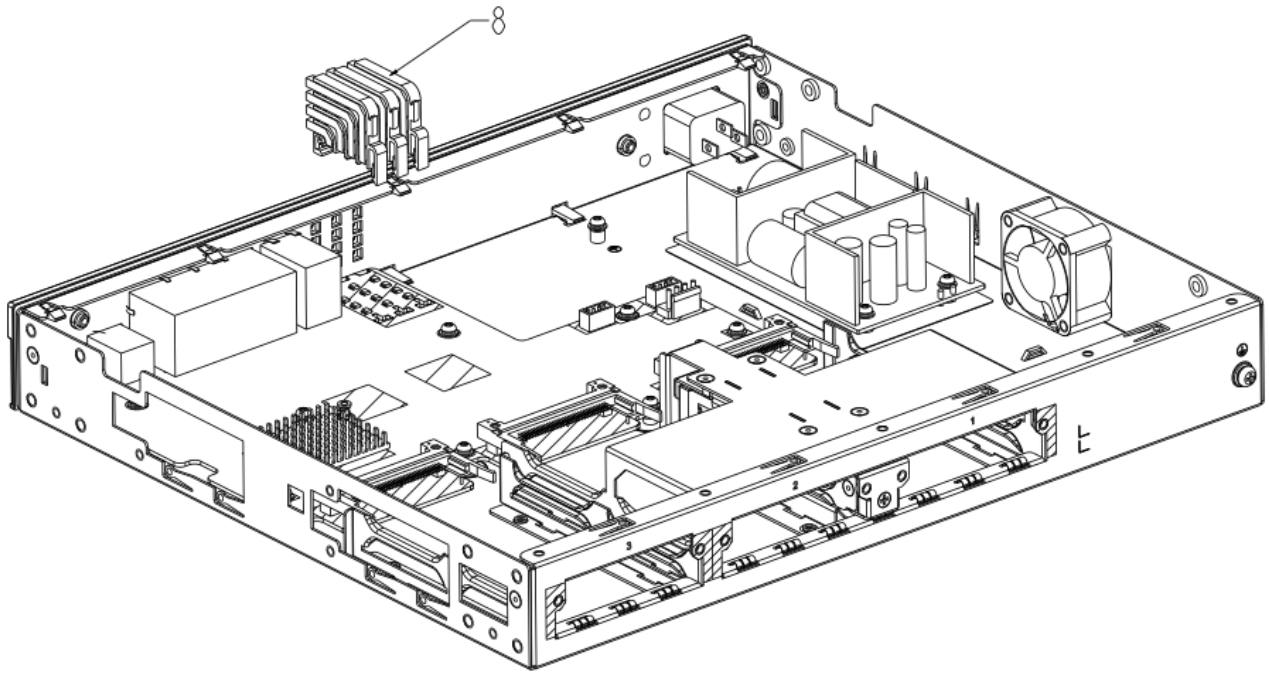

Figure 4 Treatments to the product

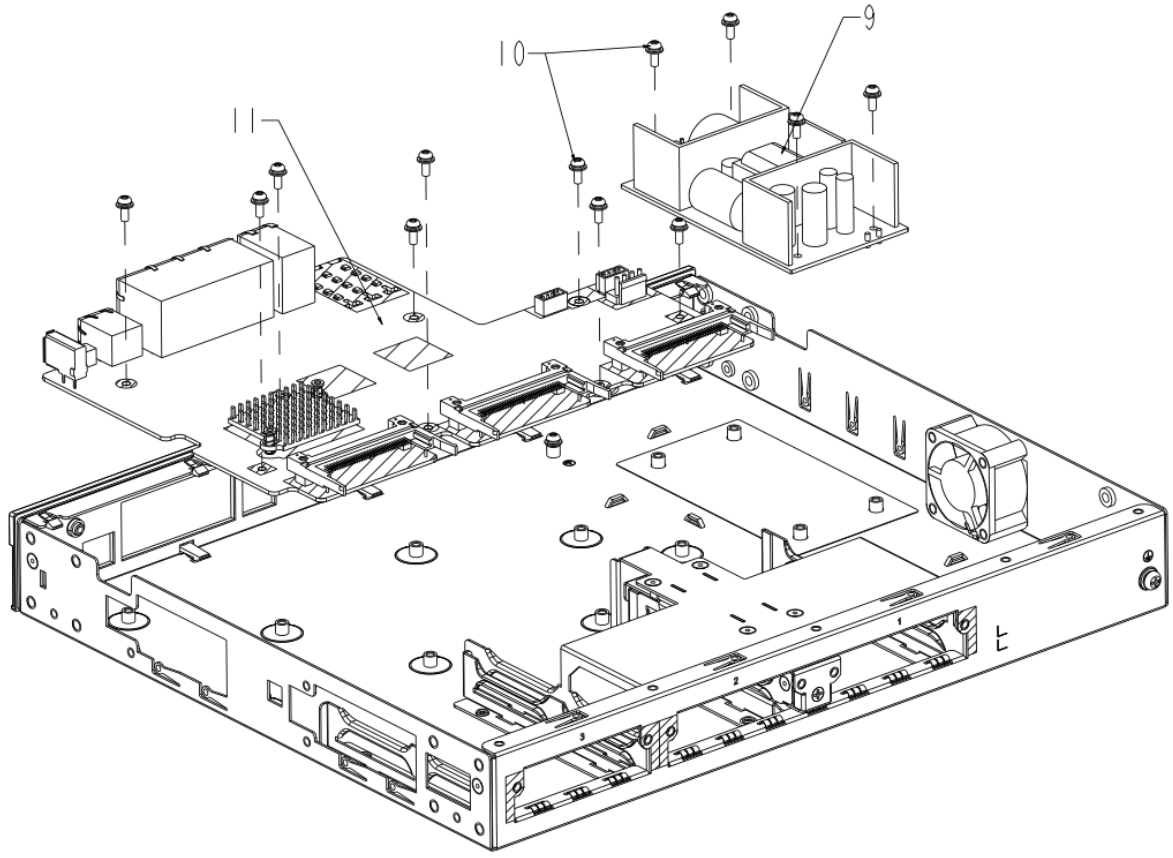

Figure 5 Treatments to product

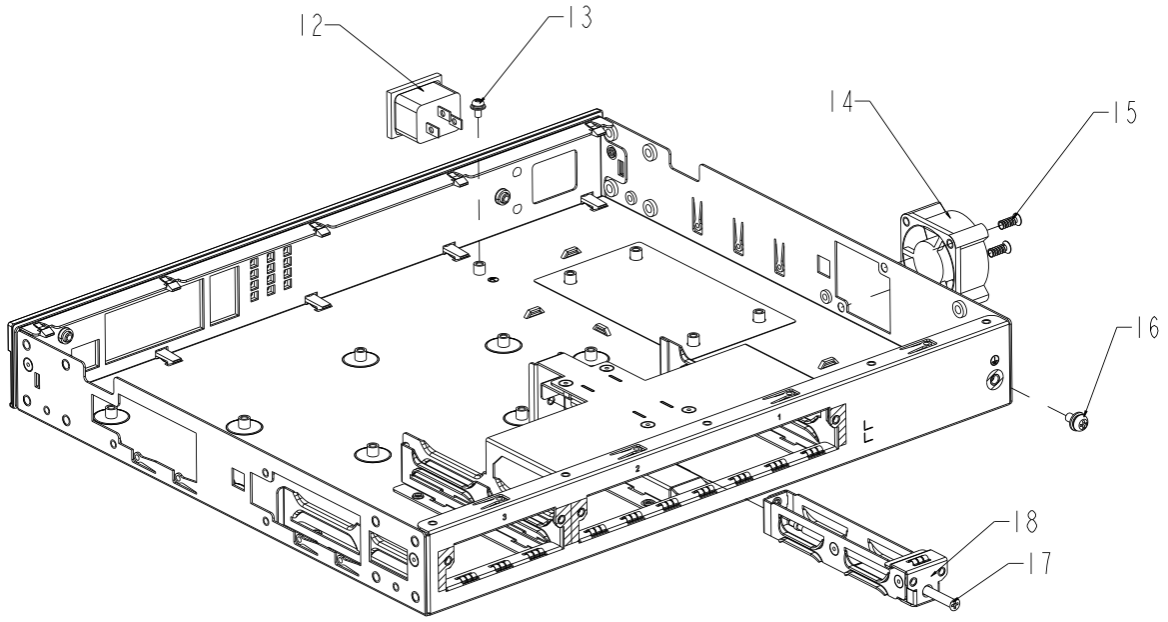

Figure 6 Treatments to the product

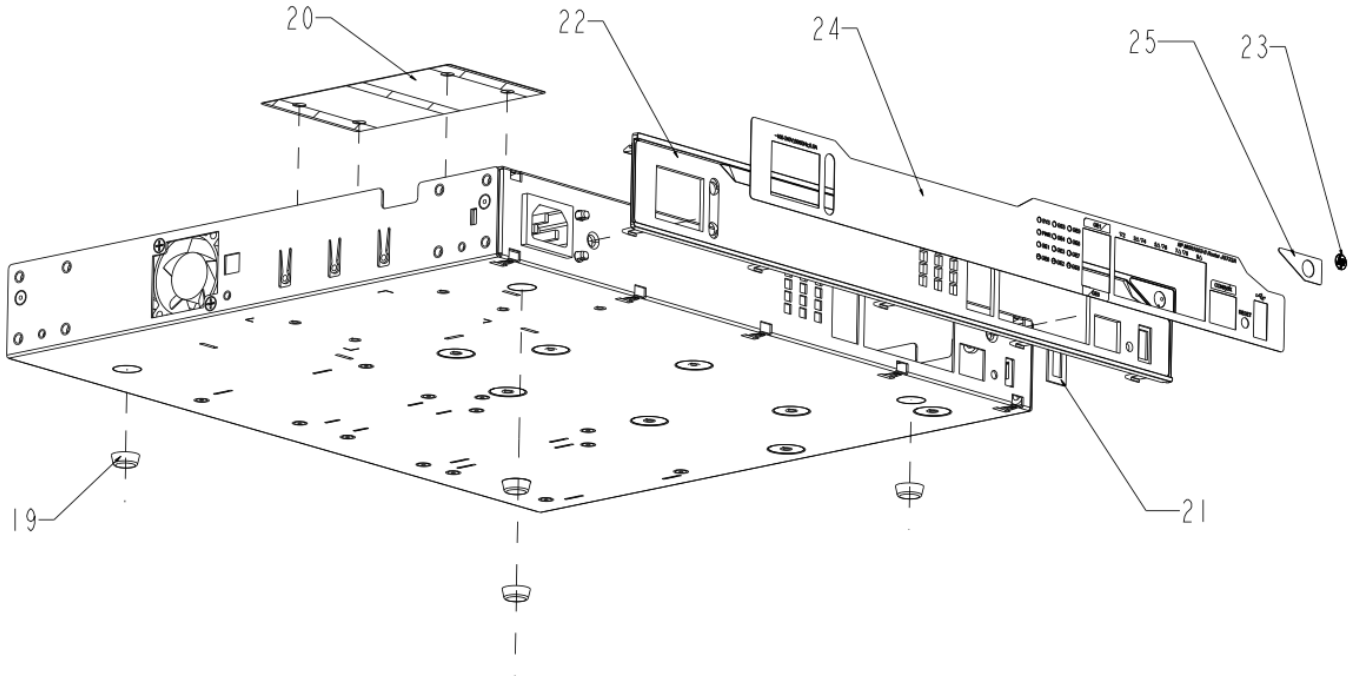

Figure 7 Treatments to product

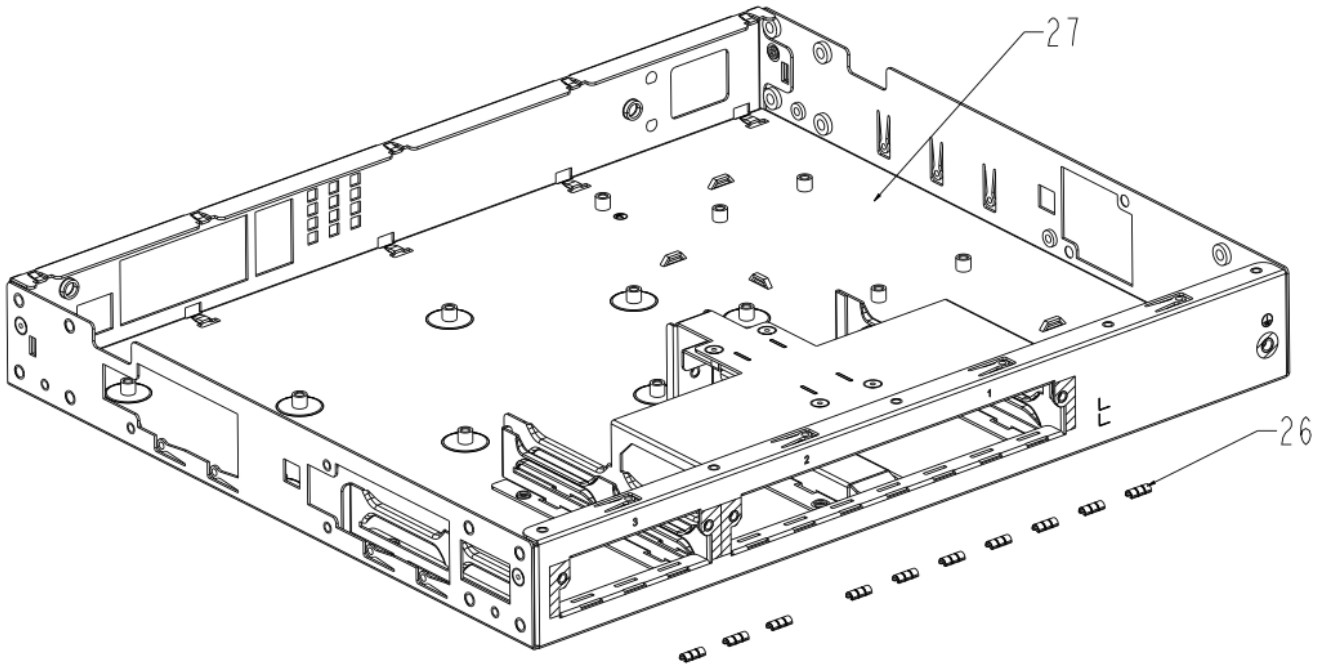

Figure 8 Treatments to product

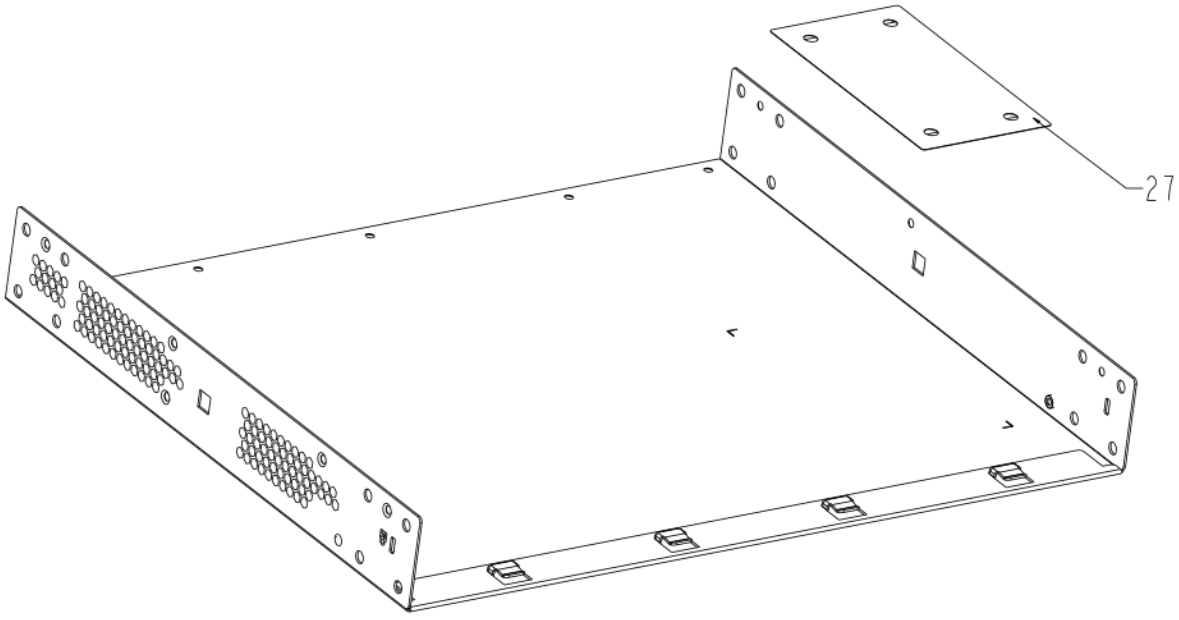

Figure 9 Treatments to top cover

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
2		Fe	121.1	3%		Fe recycling
3		Be-Cu	0.0329*6	0.005%		Cu recycling
4		Fe	17.4*3	1.3%		Fe recycling
7		Fe	1112	27.8%		Fe recycling
11		Complex PCB	1214	30.3%	The surface of PCB is greater than 10 square centimeters;	
14		PBT , Cu	41.4	1.3%	Containing brominated flame retardants	
17		Fe	12.5	0.3%		Fe recycling
18		Fe	52.2	1.3%		Fe recycling
26		Be-Cu	0.0329*10	0.008%		Cu recycling
27		Fe	1521	38%		Fe recycling

4.0 Revised record

Date	Version	Author	Modify content
2013.8.27	V0	Zhong Yali	Initial version
2014.4.18	V1	Yang Hongming	ADD JG875A(0235A1CG)